

Publikationen

(2016): Differential Wideband Interconnects for Organic Millimeter Wave Chip Packages. An effort to design an all-purpose RF chip package. In: Proceedings of the 11th European Microwave Integrated Circuits Conference 2016 (October 03-04 2016, London, UK).

(2016): Differential Wideband Interconnects for Organic Millimeter Wave Chip Packages. An effort to design an all-purpose RF chip package. In: Proceedings of the 46th European Microwave Conference (EuMC)/European Microwave Week (EuMW) 2016 (October 03-07 2016, London, UK).

(2015): Wideband RF interconnects for organic chip packages comparison of single ended and differential transitions. An effort to design an all-purpose RF chip package. In: Proceedings of the 45th European Microwave Conference (EuMC)/European Microwave Week (EuMW) 2015 (September 06-11 2015, Paris, France).

(2013): Embedded Resistors for High Frequency Applications on Printed Circuit Boards. In: Proceedings of the 43rd European Microwave Conference, Nürnberg, 06.-11.10.2013.